

AMP-LEAF

TE Internal #: 60151-6

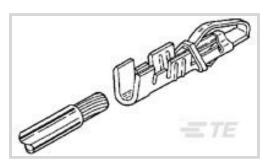
Connector Contact, Socket, Wire-to-Board, 16 AWG Wire Size, 2583 CMA Wire Size, 1.25 – 1.4 mm² Wire Size, Gold, Strip, Wire &

Cable, 5 A

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Connectors > PCB Connectors > Wire-to-Board Connectors > Wire-to-Board Connector Contacts



Contact Type: Socket

Connector System: Wire-to-Board

Wire Size: 1.25 – 1.4 mm²

Features

Product Type Features

Double Wire Insulation Diameter	2.03 – 4.06 mm[.08 – .16 in]	
Connector System	Wire-to-Board	
Sealable	No	
Connector & Contact Terminates To	Wire & Cable	
Electrical Characteristics		

I	nsulation Resistance	5000 ΜΩ

Contact Features

Contact Retention Within Housing	With
Wire Contact Termination Area Plating Material	Gold Flash
	30 μin
Contact Underplating Material	Nickel
PCB Contact Termination Area Plating Material	Gold Flash
Contact Base Material	Phosphor Bronze
Contact Type	Socket
Contact Mating Area Plating Material	Gold
Contact Current Rating (Max)	5 A

Termination Features

Termination Method to Wire & Cable	Crimp	

Mechanical Attachment



Contact Retention Type Within Housing	Locking Lance		
Wire Insulation Support	With		
Dimensions			
Accepts Wire Insulation Diameter Range	2.74 mm[.108 in]		
Wire Size	1.25 – 1.4 mm ²		
Usage Conditions			
Operating Temperature Range	-40 - 85 °C[-40 - 185 °F]		
Operation/Application			
Circuit Application	Power & Signal		
Packaging Features			
Packaging Quantity	4000		
Packaging Method	Strip		

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2022 (223) Candidate List Declared Against: JUL 2021 (219) SVHC > Threshold: Not Yet Reviewed
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Not applicable for solder process capability

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides



on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts



Customers Also Bought



















Documents

Product Drawings

AMP LEAF STRIP CONTACT

English



Datasheets & Catalog Pages

POWER_CONNECTORS_CATALOG_SEC02_CABLE_MOUNTED

English

Product Specifications

Application Specification

English

Application Specification

Japanese

AMP-LEAF Contact

English

Application Specification

Japanese

AMP-LEAF Contacts

Japanese